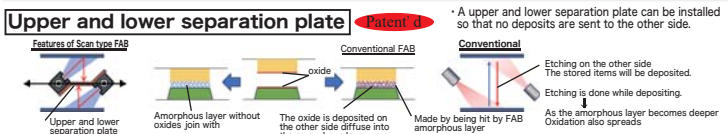
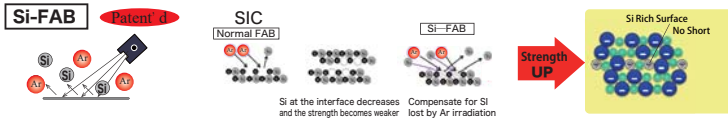
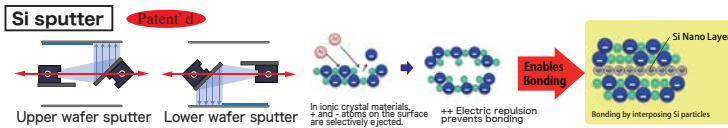


WOW

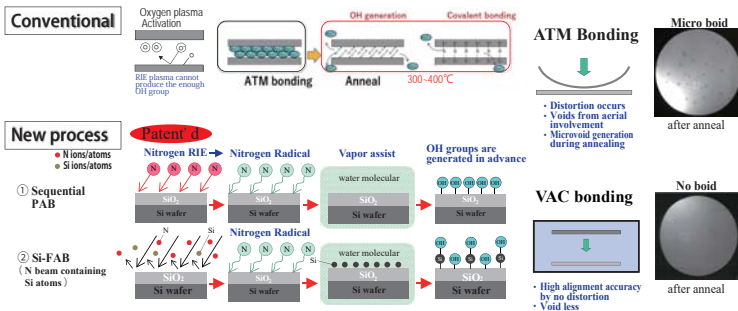


① Room temperature direct bonding in ultra high vacuum

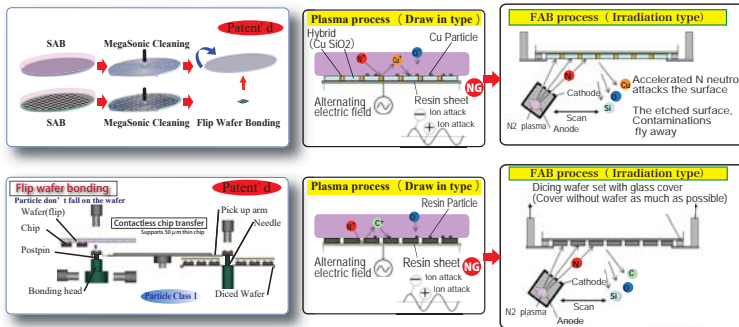
Machine configuration and bonding process



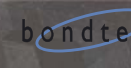
② Hydrophilic bonding in Vacuum



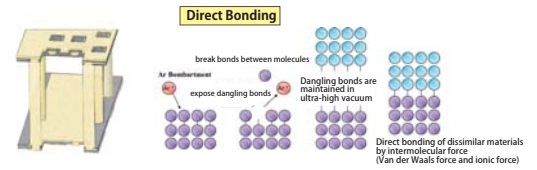
③ Surface activated Bonding COW for Semiconductor front end



COW



Cu-Cu Hybrid Bonding



±0.2μm

WF-3000

Ar Bombardment in UHV

- Line type Beam source
- Si sputter
- Si-FAB
- Ar beam containing Si atoms
- 300mm Wafer CTC Auto handling
- 6min/wafer



CIS,Memory

±0.2μm

HBWS-3000

- Sequential PAB
- Si-FAB
- Particle cleaning
- 300mm Wafer CTC Auto handling
- 15-20 WPH



Logic,Memory,CIS

±0.2μm

HBCW-3000

- Alignment accuracy ± 0.2μm
- FAB activation treatment
- Particle cleaning (Mega sonic)
- 300mm wafer CTC automatic handling



High Accuracy Alignment System

WOW



COW

